



## Material Content Data Sheet



Sales Product Name	BSS215P H6327			Issued		12. December 2019		
MA#	MA001232390							
Package	PG-SOT23-3-5			Weight*		9.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.05		470	
	noble metal	gold	7440-57-5	0.017	0.18		1823	
	inorganic material	silicon	7440-21-3	0.194	2.07	2.30	20660	22953
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		64	
	non noble metal	titanium	7440-32-6	0.003	0.03		321	
	non noble metal	chromium	7440-47-3	0.009	0.10		963	
	non noble metal	copper	7440-50-8	3.000	31.98	32.12	319761	321109
wire	non noble metal	copper	7440-50-8	0.044	0.47	0.47	4699	4699
encapsulation	organic material	carbon black	1333-86-4	0.057	0.60		6050	
	plastics	epoxy resin	-	1.220	13.01		130071	
	inorganic material	silicondioxide	60676-86-0	4.399	46.88	60.49	468858	604979
leadfinish	non noble metal	tin	7440-31-5	0.150	1.59	1.59	15948	15948
plating	noble metal	silver	7440-22-4	0.284	3.03	3.03	30312	30312
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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